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**Press-Fit Standard for Automotive
Requirements and Other
High-Reliability Applications**

An international standard developed by IPC



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Developed by the Cold Joining Press-Fit Task Group (5-21m) of the
Assembly and Joining Committee (5-20) of IPC

Users of this publication are encouraged to participate in the
development of future revisions.

Contact:

IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

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Assembly and Joining Committee	Cold Joining Press-Fit Task Group	Technical Liaison of the IPC Board of Directors
Chair Daniel Foster Missile Defense Agency Vice Chair Karen A. Tellefsen MacDermid Alpha Electronics Solutions	Co-Chairs Hans-Peter Trantz Continental Automotive GmbH Udo Welzel Robert Bosch GmbH	Bob Neves Microtek (Changzhou) Laboratories
Cold Joining Press-Fit Task Group		
David C. Adams, Collins Aerospace Thomas Ahrens, Trainalytics GmbH Randy Alexander, CTS Corporation Frederick P. Beltran, L3Harris Communications Martin Bleicher, TE Connectivity Germany GmbH William Bowers, ZF TRW Automotive Bjoern Bretthauer, INOVAN GmbH & Co. KG Marc Brodbeck, Würth Elektronik ICS GmbH & Co. KG Jay Brusse, SSAI at NASA Goddard Space Flight Center Andreas Buehrle, Wieland-Werke AG Giovanni Casanova, Schweitzer Engineering Laboratories, Inc. Zhiman Chen, Zhuzhou CRRC Time Electric Co., Ltd. Lenora M. Clark, MacDermid Alpha Electronics Solutions Charles Copper, FCI USA, Inc. Erika Crandall, TE Connectivity Germany GmbH Philip Dancison, Delphi Automotive Pascal Dumortier, Renault Technocentre Cole Dunn, Plexus Corporation Michael Durkan, Mentor Graphics Corporation Juergen Egervari, IMOC Electronic Components (Changzhou) Co., Ltd. Hermann Eicher, EPT Guglhoer GmbH	Bernd Eifer, ERNI Elektroapparate GmbH Juergen Friedrich, ERSA GmbH Hugo GARCIA, Airbus Defence & Space Joachim Giuriato, Molex Elektronik GmbH Andrew Goddard, ZF Automotive UK Limited Constantino Jose Gonzalez, ACME Training & Consulting Thomas Gottwald, Schweizer Electronic AG Arnau Griven, Thales Global Services Michael Haas, ERSA GmbH Lutz Haase, HELLA GmbH & Co. KGaA Stefan Hanigk, Ariane Group GmbH Alafio Hewitt, Lockheed Martin Missiles & Fire Control Gaston Hidalgo, Toyota Motor North America Angela Mary Higgins, Molex Ireland Ltd. Charles Hirbour, Technic Inc. Emma Hudson, Emma Hudson Technical Consultancy Ltd Philippe Jaeckle, Robert Bosch GmbH Rajesh Jayaraj, Webasto Roof & Components SE Satoshi Kashiwabara, Toyota Motor Corporation Daniel Klenk, Nexteer Automotive Yusaku Kono, Japan Unix Co., Ltd.	Chandan Neetha Kumar, Interplex Precision Technology (Singapore) Pte.Ltd. Dimmar Kurzeja, Possehl Electronics Hugues Lenormand, Veoneer Francois Le-Rest, Continental Automotive France SAS Joseph Lynch, Interplex Industries, Inc Chris Mahanna, Robisan Laboratory Inc. Jean-Francois Mahe, LCO Michael Meckl, Interplex Industries, Inc Amit Mensi, Molex, LLC Julien Michau, Sonceboz SA Steve Minich, Amphenol InterCon Systems Shota Mishima, Toyota Motor Corporation Werner MORITZ, iwis smart connect GmbH Kristopher Moyer Wolfgang Neef, ELCO Europe GmbH Thi V. Nguyen, Lockheed Martin Missile & Fire Control Jason Nipper, UTC Aerospace Systems James O'Connor, IBM Corporation Andres Ojalill, Tallinn Polytechnic School Brad Palmer, John Deere Electronic Solutions, Inc. Timothy John Pearson, Collins Aerospace Jan Pedersen, Elmatica AS

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 Flight Center

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 Missile Command
 Toshiyasu Takei, Japan Unix Co., Ltd.
 Friedrich Talgner, Umicore
 TATSUROH TANAKA, Toyota Motor
 Corporation
 Pascal Thibaut, Sonceboz SA
 John Paul Thompson, FCI USA, Inc.
 Hans-Peter Tranitz, Continental
 Automotive GmbH
 Juergen Turnsek, HAERTER
 Frank Uibel, Uibel Consulting
 Jose Maria Vallez Ramos, Webasto
 Roof & Components SE

Lutz Weber, ZF Automotive UK Limited
 Benjamin Wehl, Nexteer Automotive
 Michael Kurt Weinhold, PLUS
 Leiterplatten G
 Udo Welzel, Robert Bosch GmbH
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 Technologies Corp.
 Dennis Willie, Flextronics International
 Volker Wohlfarth, Umicore
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Press-Fit Standard for Automotive Requirements and Other High-Reliability Applications

1 Scope This standard prescribes practices for the characterization, qualification and acceptance requirements of compliant press-fit technology for printed boards that cover the manufacturability and reliability needs for high reliability applications intended for use in harsh environments such as automotive and aerospace.

Additional requirements for aerospace applications in Appendix B may apply.

1.1 Purpose This standard prescribes practices for the characterization, qualification and acceptance requirements of compliant press-fit technology for printed boards.

Standards may be updated at any time, including with the use of amendments. The use of an amendment or newer revision is not automatically required. The revision in effect **shall** be as specified by the user.

1.2 Classification

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically, the end-use environment would not cause failures.

CLASS 3 High Performance/Harsh Environment Electronic Products

Includes products where continued high performance or performance on demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

All requirements in this standard pertain to IPC Class 3. When this standard is contractually required, IPC Class 3 requirements **shall** be adopted for all other contractually required standards.

1.3 Measurement Units This standard uses International System of Units (SI units) per ASTM SI10, IEEE/ASTM SI 10, Section 3 [Imperial English equivalent units are in brackets for convenience]. The SI units used in this standard are millimeters (mm) [in] for dimensions and dimensional tolerances, Celsius (°C) [°F] for temperature and temperature tolerances, grams (g) [oz] for weight, and lumens (lm) [footcandles] for illuminance.

Note: This standard uses other SI prefixes (ASTM SI10, Section 3.2) to eliminate leading zeroes (for example, 0.0012 mm becomes 1.2 μm) or as an alternative to powers-of-ten (3.6×10^3 mm becomes 3.6 m).

1.3.1 Verification of Dimensions When an inspection is done on an assembly, measuring dimensions and determining percentages listed in the standard are not required unless there is a doubt or a question is raised about the acceptance of the product. When there is a doubt or a question is raised, then a referee determination should be implemented, at which time measurements should be made or percentages calculated using the referee magnifications defined in the Standard. For determining conformance to the specifications in this standard, round all observed or calculated values "to the nearest unit" in the last right-hand digit used in expressing the specification limit, in accordance with the rounding method of ASTM Practice E29. For example, specifications of 2.5 mm max, 2.50 mm max, or 2.500 mm max, round the measured value to the nearest 0.1 mm, 0.01 mm, or 0.001 mm, respectively, and then compare to the specification number cited.

1.4 Definition of Requirements The words "**shall**" or "**shall not**" are used in the text of this document wherever there is a requirement for materials, preparation, process control or acceptance.

The word "should" reflects recommendations and is used to reflect general industry practices and procedures for guidance only.

Line drawings and illustrations are depicted herein to assist in the interpretation of the written requirements of this standard. The text takes precedence over the figures.